

1AP20 Rec'd PCT/PTO 19 JAN 2006

FORM PTO-1449	SERIAL NO. Not Yet Assigned	CASE NO. 10/565,623 05/37 2815, 144/US
LIST OF PATENTS AND PUBLICATIONS FOR APPLICANT'S INFORMATION DISCLOSURE STATEMENT	FILING DATE Herewith	GROUP ART UNIT Not Yet Assigned
APPLICANTS: MORICEAU et al.		

REFERENCE DESIGNATION U.S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER <small>Number-Kind Code (if known)</small>	DATE	NAME	CLASS/ SUBCLASS	FILING DATE
RSP	A1	US 2002/0145489 A1	10/10/2002	Cornett et al.	—	
RSP	A2	6,198,159 B1	03/06/2001	Hosoma et al.	—	
RSP	A3	5,259,247	11/09/1993	Bantien	—	

FOREIGN PATENT DOCUMENT

EXAMINER INITIAL		DOCUMENT NUMBER <small>Number-Kind Code (if known)</small>	DATE	COUNTRY	CLASS/ SUBCLASS	TRANSLATION YES OR NO
RSP	A4	FR 2 797 347 A1	02/09/2001	France	—	Abstract only
RSP	A5	FR 2 736934 A1	01/24/1997	France	—	Abstract only
RSP	A6	FR 2 681 472 A1	03/19/1993	France	—	Abstract only
RSP	A7	FR 2 558 263 A1	07/19/1985	France	—	Abstract only
RSP	A8	EP 0 754 953 B1	06/20/2001	EPO	—	Abstract only

OTHER ART - NON PATENT LITERATURE DOCUMENTS

EXAMINER INITIAL		(Include name of author, title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date page(s), volume-issue number(s), publisher, city and/or country where published.
RSP	A9	Alley et al., "Surface Roughness Modification of Interfacial Contacts in Polysilicon Microstructures", Proceedings of the 7 <sup>th</sup> International Conference on Solid-State Sensors and Actuators, "Transducers '93," pp. 288-291, June 7-10, 1993, PACIFICO, Yokohama, Japan.
RSP	A10	Aspar et al., "The Generic Nature of the Smart-Cut <sup>®</sup> Process for Thin-film Transfer", Journal of Electronic Materials, Vol. 30, No. 7, pp. 834-840, 2001.
RSP	A11	Diem et al., "SOI 'SIMOX'; from bulk to surface micromachining, a new age for silicon sensors and actuators", Sensors and Actuators, Vol. A 46 - 47, pp. 8-16, 1995.
RSP	A12	Goesele et al., "Semiconductor Wafer Bonding", Science and Technology, ECS Series, New Jersey 1999, Annual Review of Material Science, Vol. 28, pp. 215-241, 1998.

EXAMINER <i>Am. S. Porter</i>	DATE CONSIDERED 5/11/07
-------------------------------	-------------------------

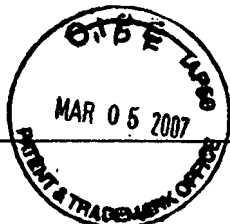
EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

FORM PTO-1449	SERIAL NO. Not Yet Assigned	10/565621 950537 (BIF116044/US)
LIST OF PATENTS AND PUBLICATIONS FOR APPLICANT'S INFORMATION DISCLOSURE STATEMENT	FILING DATE Herewith	GROUP ART UNIT Not Yet Assigned
(use several sheets if necessary)	APPLICANTS: MORICEAU et al.	

EXAMINER INITIAL	OTHER ART - NON PATENT LITERATURE DOCUMENTS (Include name of author, title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date page(s), volume-issue number(s), publisher, city and/or country where published.	
RSP	A13	Liu et al., "Investigation of Interface in Silicon-on-Insulator by Fractal Analysis," <i>Applied Surface Science</i> , 187, pp. 187-191, 2002.
RSP	A14	Schnell et al., "Plasma Surface Texturization for Multicrystalline Silicon Solar Cells", IEEE, XXVIII <sup>th</sup> Photovoltaic Conference, pp. 367-370, 2000.
RSP	A15	Mastrangelo, C.H., "Suppression of Stiction in MEMS", Proceedings of the Materials Research Society Seminar, Vol. 605, pp. 1-12, 2000.
RSP	A16	Yee et al., "Polysilicon Surface-Modification Technique to Reduce Sticking of Microstructures," <i>Sensors and Actuators A</i> 52, pp. 145-150, 1996.

EXAMINER <i>hms. Patel</i>	DATE CONSIDERED 5/11/07
----------------------------	-------------------------

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.



FORM PTO-1449	SERIAL NO. 10/565,621	CASE NO. 9905/37 (BIF116044/US)
LIST OF PATENTS AND PUBLICATIONS FOR APPLICANT'S INFORMATION DISCLOSURE STATEMENT	FILING DATE July 25, 2006	GROUP ART UNIT 2812
(use several sheets if necessary)		APPLICANT(S): Moriceau et al.

**FOREIGN PATENT DOCUMENTS**

EXAMINER INITIAL		DOCUMENT NUMBER <small>Number-Kind Code (if known)</small>	DATE	COUNTRY	CLASS/ SUBCLASS	TRANSLATION YES OR NO
RSP	B1	95 08882	July 21, 1995	France	—	Yes abstract only

EXAMINER INITIAL	<b>OTHER ART – NON PATENT LITERATURE DOCUMENTS</b> <small>(Include name of author, title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date page(s), volume-issue number(s), publisher, city and/or country where published.)</small>	
RSP	B2	Fujitsuka et al., "A new processing technique to prevent stiction using silicon selective etching for SOT-MEMS", Sensors and Actuators, A97-98, pp. 716-719, 2002
RSP	B3	Ashurst et al., "Wafer level anti-stiction coatings for MEMS", Sensors and Actuators A104, pp. 213-221, 2003
	B4	
	B5	
	B6	
	B7	

EXAMINER		DATE CONSIDERED	5/11/07
----------	---	-----------------	---------

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.



FORM PTO-1449	SERIAL NO. 10/565,621	CASE NO. 9905/37
LIST OF PATENTS AND PUBLICATIONS FOR APPLICANT'S INFORMATION DISCLOSURE STATEMENT	FILING DATE July 25, 2006	GROUP ART UNIT 2812
(use several sheets if necessary)	APPLICANT(S): Moriceau et al.	

## REFERENCE DESIGNATION

## U.S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER <small>Number-Kind Code (if known)</small>	DATE	NAME	CLASS/ SUBCLASS	FILING DATE
RSP	C1	6,156,215	12/05/2000	Shimada et al.		

EXAMINER: <i>[Signature]</i>	DATE CONSIDERED: 5/11/07
------------------------------	--------------------------

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.